ON Semiconductor

Is Now

To learn more about onsemi™, please visit our website at
www.onsemi.com

MC74AC109, MC74ACT109

Dual $J\overline{K}$ Positive Edge-Triggered Flip-Flop

The MC74AC109/74ACT109 consists of two high−speed completely independent transition clocked $J\overline{K}$ flip−flops. The clocking operation is independent of rise and fall times of the clock waveform. The $J\overline{K}$ design allows operation as a D flip−flop (refer to MC74AC74/74ACT74 data sheet) by connecting the J and $\overline{K}$ inputs together.

Asynchronous Inputs:

LOW input to $\overline{S}_D$ (Set) sets Q to HIGH level
LOW input to $\overline{C}_D$ (Clear) sets Q to LOW level
Clear and Set are independent of clock
Simultaneous LOW on $\overline{C}_D$ and $\overline{S}_D$ makes both Q and $\overline{Q}$ HIGH

- Outputs Source/Sink 24 mA
- ′ACT109 Has TTL Compatible Inputs

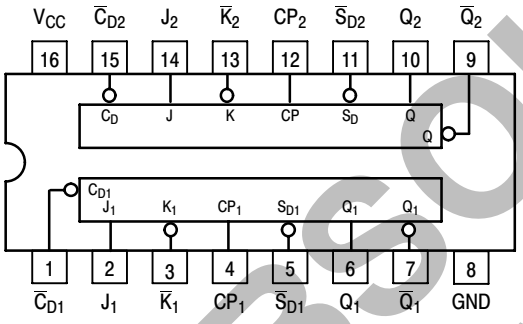


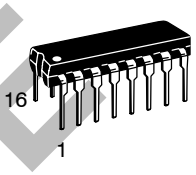
Figure 1. Pinout; 16−Lead Packages Conductors
(Top View)

PIN ASSIGNMENT

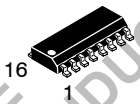
PIN	FUNCTION
J_1, J_2, $\overline{K}_1$, $\overline{K}_2$	Data Inputs
CP_1, CP_2	Clock Pulse Inputs
$\overline{C}_{D1}$, $\overline{C}_{D2}$	Direct Clear Inputs
$\overline{S}_{D1}$, $\overline{S}_{D2}$	Direct Set Inputs
Q_1, Q_2, $\overline{Q}_1$, $\overline{Q}_2$	Outputs

ON Semiconductor™

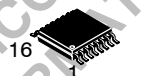
http://onsemi.com



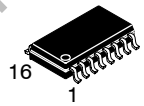
DIP−16
N SUFFIX
CASE 648



SO−16
D SUFFIX
CASE 751B



TSSOP−16
DT SUFFIX
CASE 948F



EIAJ−16
M SUFFIX
CASE 966

ORDERING INFORMATION

Device	Package	Shipping
MC74AC109N	PDIP−16	25 Units/Rail
MC74ACT109N	PDIP−16	25 Units/Rail
MC74AC109D	SOIC−16	48 Units/Rail
MC74ACT109D	SOIC−16	48 Units/Rail
MC74AC109DR2	SOIC−16	2500 Tape & Reel
MC74ACT109DR2	SOIC−16	2500 Tape & Reel
MC74AC109DT	TSSOP−16	96 Units/Rail
MC74ACT109DT	TSSOP−16	96 Units/Rail
MC74AC109DTR2	TSSOP−16	2500 Tape & Reel
MC74ACT109DTR2	TSSOP−16	2500 Tape & Reel
MC74AC109M	EIAJ−16	50 Units/Rail
MC74ACT109M	EIAJ−16	50 Units/Rail
MC74AC109MEL	EIAJ−16	2000 Tape & Reel
MC74ACT109MEL	EIAJ−16	2000 Tape & Reel

DEVICE MARKING INFORMATION

See general marking information in the device marking section on page 6 of this data sheet.

TRUTH TABLE

Inputs					Outputs	
$\overline{S}_D$	$\overline{C}_D$	CP	J	$\overline{K}$	Q	$\overline{Q}$
L	H	X	X	X	H	L
H	L	X	X	X	L	H
L	L	X	X	X	H	H
H	H	⌐	L	L	L	H
H	H	⌐	H	L	Toggle	
H	H	⌐	L	H	Q_0	$\overline{Q}_{0-}$
H	H	⌐	H	H	H	L
H	H	L	X	X	Q_0	$\overline{Q}_{0-}$

H = HIGH Voltage Level
L = LOW Voltage Level
⌐ = LOW−to−HIGH Clock Transition
X = Immaterial
$Q_0(\overline{Q}_0)$ = Previous $Q_0(\overline{Q}_0)$ before LOW−to−HIGH Transition of Clock

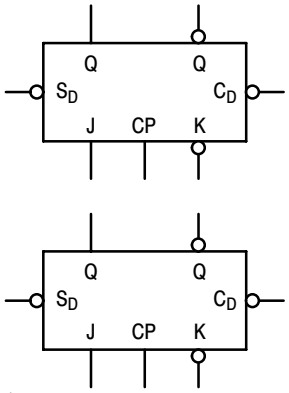
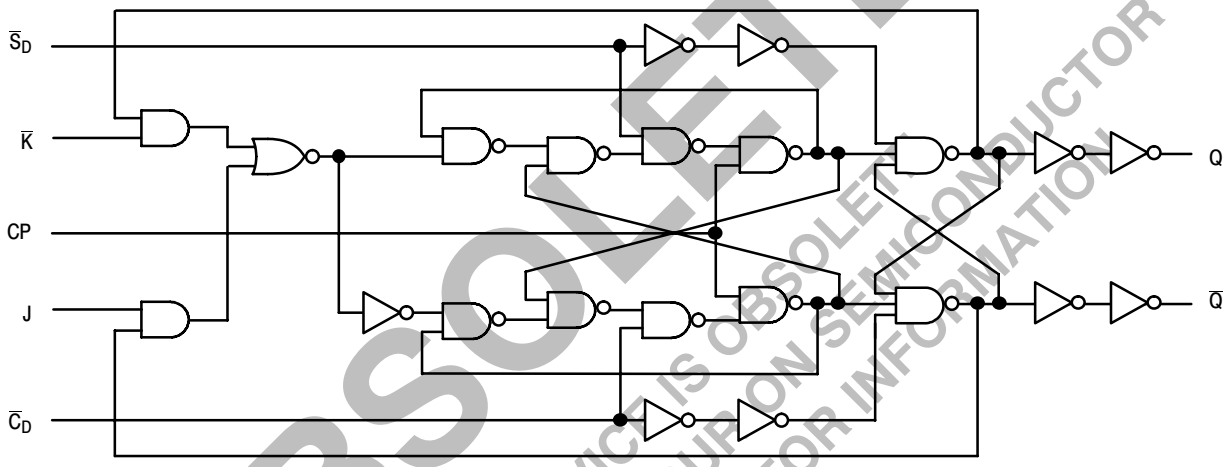


Figure 2. Logic Symbol



NOTE: This diagram is provided only for the understanding of logic operations and should not be used to estimate propagation delays.

Figure 3. Logic Diagram
(One Half Shown)

MAXIMUM RATINGS*

Symbol	Parameter	Value	Unit
V_{CC}	DC Supply Voltage (Referenced to GND)	−0.5 to +7.0	V
V_{IN}	DC Input Voltage (Referenced to GND)	−0.5 to V_{CC} +0.5	V
V_{OUT}	DC Output Voltage (Referenced to GND)	−0.5 to V_{CC} +0.5	V
I_{IN}	DC Input Current, per Pin	±20	mA
I_{OUT}	DC Output Sink/Source Current, per Pin	±50	mA
I_{CC}	DC V_{CC} or GND Current per Output Pin	±50	mA
T_{stg}	Storage Temperature	−65 to +150	°C

*Maximum Ratings are those values beyond which damage to the device may occur. Functional operation should be restricted to the Recommended Operating Conditions.

RECOMMENDED OPERATING CONDITIONS

Symbol	Parameter		Min	Typ	Max	Unit
V_{CC}	Supply Voltage	′AC	2.0	5.0	6.0	V
		′ACT	4.5	5.0	5.5	
V_{IN}, V_{OUT}	DC Input Voltage, Output Voltage (Ref. to GND)		0	–	V_{CC}	V
t_r, t_f	Input Rise and Fall Time (Note 1) ′AC Devices except Schmitt Inputs	V_{CC} @ 3.0 V	–	150	–	ns/V
		V_{CC} @ 4.5 V	–	40	–	
		V_{CC} @ 5.5 V	–	25	–	
t_r, t_f	Input Rise and Fall Time (Note 2) ′ACT Devices except Schmitt Inputs	V_{CC} @ 4.5 V	–	10	–	ns/V
		V_{CC} @ 5.5 V	–	8.0	–	
T_J	Junction Temperature (PDIP)		–	–	140	°C
T_A	Operating Ambient Temperature Range		–40	25	85	°C
I_{OH}	Output Current – High		–	–	–24	mA
I_{OL}	Output Current – Low		–	–	24	mA

1. V_{IN} from 30% to 70% V_{CC}; see individual Data Sheets for devices that differ from the typical input rise and fall times.
2. V_{IN} from 0.8 V to 2.0 V; see individual Data Sheets for devices that differ from the typical input rise and fall times.

DC CHARACTERISTICS

Symbol	Parameter	V_{CC} (V)	74AC T_A = +25°C		74AC T_A = –40°C to +85°C	Unit	Conditions
			Typ	Guaranteed Limits			
V_{IH}	Minimum High Level Input Voltage	3.0	1.5	2.1	2.1	V	V_{OUT} = 0.1 V or V_{CC} – 0.1 V
		4.5	2.25	3.15	3.15		
		5.5	2.75	3.85	3.85		
V_{IL}	Maximum Low Level Input Voltage	3.0	1.5	0.9	0.9	V	V_{OUT} = 0.1 V or V_{CC} – 0.1 V
		4.5	2.25	1.35	1.35		
		5.5	2.75	1.65	1.65		
V_{OH}	Minimum High Level Output Voltage	3.0	2.99	2.9	2.9	V	I_{OUT} = –50 μA
		4.5	4.49	4.4	4.4		
		5.5	5.49	5.4	5.4		
		3.0	–	2.56	2.46	V	*V_{IN} = V_{IL} or V_{IH} I_{OH} –12 mA
		4.5	–	3.86	3.76		I_{OH} –24 mA
		5.5	–	4.86	4.76		I_{OH} –24 mA
V_{OL}	Maximum Low Level Output Voltage	3.0	0.002	0.1	0.1	V	I_{OUT} = 50 μA
		4.5	0.001	0.1	0.1		
		5.5	0.001	0.1	0.1		
		3.0	–	0.36	0.44	V	*V_{IN} = V_{IL} or V_{IH} I_{OL} 12 mA
		4.5	–	0.36	0.44		I_{OL} 24 mA
		5.5	–	0.36	0.44		I_{OL} 24 mA
I_{IN}	Maximum Input Leakage Current	5.5	–	±0.1	±1.0	μA	V_I = V_{CC}, GND
I_{OLD}	†Minimum Dynamic Output Current	5.5	–	–	75	mA	V_{OLD} = 1.65 V Max
I_{OHD}		5.5	–	–	–75	mA	V_{OHD} = 3.85 V Min
I_{CC}	Maximum Quiescent Supply Current	5.5	–	4.0	40	μA	V_{IN} = V_{CC} or GND

*All outputs loaded; thresholds on input associated with output under test.
†Maximum test duration 2.0 ms, one output loaded at a time.

NOTE: I_{IN} and I_{CC} @ 3.0 V are guaranteed to be less than or equal to the respective limit @ 5.5 V V_{CC}.

AC CHARACTERISTICS (For Figures and Waveforms − See Section 3 of the ON Semiconductor FACT Data Book, DL138/D)

Symbol	Parameter	V_{CC}* (V)	74AC T_A = +25°C C_L = 50 pF			74AC T_A = −40°C to +85°C C_L = 50 pF		Unit	Fig. No.
			Min	Typ	Max	Min	Max		
f_{max}	Maximum Clock Frequency	3.3 5.0	125 150	– –	– –	100 125	– –	MHz	3–3
t_{PLH}	Propagation Delay CP_n to Q_n or $\overline{Q}_n$	3.3 5.0	4.0 2.5	– –	13.5 10.0	3.5 2.0	16.0 10.5	ns	3–6
t_{PHL}	Propagation Delay CP_n to Q_n or $\overline{Q}_n$	3.3 5.0	3.0 2.0	– –	14.0 10.0	3.0 1.5	14.5 10.5	ns	3–6
t_{PLH}	Propagation Delay $\overline{C}_{Dn}$ or $\overline{S}_{Dn}$ to Q_n or $\overline{Q}_n$	3.3 5.0	3.0 2.5	– –	12.0 9.0	2.5 2.0	13.0 10.0	ns	3–6
t_{PHL}	Propagation Delay $\overline{C}D_n$ or $\overline{S}_{Dn}$ to Q_n or $\overline{Q}_n$	3.3 5.0	3.0 2.0	– –	12.0 9.5	3.0 2.0	13.5 10.5	ns	3–6

*Voltage Range 3.3 V is 3.3 V ±0.3 V.
*Voltage Range 5.0 V is 5.0 V ±0.5 V.

AC OPERATING REQUIREMENTS

Symbol	Parameter	V_{CC}* (V)	74AC T_A = +25°C C_L = 50 pF		74AC T_A = −40°C to +85°C C_L = 50 pF	Unit	Fig. No.
			Typ	Guaranteed Minimum			
t_s	Set−up Time, HIGH or LOW J_n or $\overline{K}_n$ to CP_n	3.3 5.0	– –	6.5 4.5	7.5 5.0	ns	3–9
t_h	Hold Time, HIGH or LOW J_n or $\overline{K}_n$ to CP_n	3.3 5.0	– –	0 0.5	0 0.5	ns	3–9
t_w	Pulse Width CP_n or $\overline{C}_{Dn}$ or $\overline{S}_{Dn}$	3.3 5.0	– –	4.0 3.5	4.5 3.5	ns	3–6
t_{rec}	Recovery TIme $\overline{C}_{Dn}$ or $\overline{S}_{Dn}$ to CP	3.3 5.0	– –	0 0	0 0	ns	3–9

*Voltage Range 3.3 V is 3.3 V ±0.3 V.
*Voltage Range 5.0 V is 5.0 V ±0.5 V.

DC CHARACTERISTICS

Symbol	Parameter	V_{CC} (V)	74ACT T_A = +25°C		74ACT T_A = −40°C to +85°C	Unit	Conditions
			Typ	Guaranteed Limits			
V_{IH}	Minimum High Level Input Voltage	4.5 5.5	1.5 1.5	2.0 2.0	2.0 2.0	V	V_{OUT} = 0.1 V or V_{CC} − 0.1 V
V_{IL}	Maximum Low Level Input Voltage	4.5 5.5	1.5 1.5	0.8 0.8	0.8 0.8	V	V_{OUT} = 0.1 V or V_{CC} − 0.1 V
V_{OH}	Minimum High Level Output Voltage	4.5 5.5	4.49 5.49	4.4 5.4	4.4 5.4	V	I_{OUT} = −50 μA
		4.5 5.5	– –	3.86 4.86	3.76 4.76	V	*V_{IN} = V_{IL} or V_{IH} I_{OH} −24 mA I_{OH} −24 mA

*All outputs loaded; thresholds on input associated with output under test.
†Maximum test duration 2.0 ms, one output loaded at a time.

DC CHARACTERISTICS (continued)

Symbol	Parameter	V_{CC} (V)	74ACT T_A = +25°C		74ACT T_A = –40°C to +85°C	Unit	Conditions
			Typ	Guaranteed Limits			
V_{OL}	Maximum Low Level Output Voltage	4.5 5.5	0.001 0.001	0.1 0.1	0.1 0.1	V	I_{OUT} = 50 μA
		4.5 5.5	– –	0.36 0.36	0.44 0.44	V	*V_{IN} = V_{IL} or V_{IH} I_{OL} 24 mA I_{OL} 24 mA
I_{IN}	Maximum Input Leakage Current	5.5	–	±0.1	±1.0	μA	V_I = V_{CC}, GND
ΔI_{CCT}	Additional Max. I_{CC}/Input	5.5	0.6	–	1.5	mA	V_I = V_{CC} – 2.1 V
I_{OLD}	†Minimum Dynamic Output Current	5.5	–	–	75	mA	V_{OLD} = 1.65 V Max
I_{OHD}		5.5	–	–	–75	mA	V_{OHD} = 3.85 V Min
I_{CC}	Maximum Quiescent Supply Current	5.5	–	4.0	40	μA	V_{IN} = V_{CC} or GND

*All outputs loaded; thresholds on input associated with output under test.
†Maximum test duration 2.0 ms, one output loaded at a time.

AC CHARACTERISTICS (For Figures and Waveforms – See Section 3 of the ON Semiconductor FACT Data Book, DL138/D)

Symbol	Parameter	V_{CC}* (V)	74ACT T_A = +25°C, C_L = 50 pF			74ACT T_A = –40°C to +85°C, C_L = 50 pF		Unit	Fig. No.
			Min	Typ	Max	Min	Max		
f_{max}	Maximum Clock Frequency	5.0	145	–	–	125	–	MHz	3–3
t_{PLH}	Propagation Delay CP_n to Q_n or $\overline{Q}_n$	5.0	4.0	–	11.0	3.5	13.0	ns	3–6
t_{PHL}	Propagation Delay CP_n to Q_n or $\overline{Q}_n$	5.0	3.0	–	10.0	2.5	11.5	ns	3–6
t_{PLH}	Propagation Delay $\overline{C}_{Dn}$ or $\overline{S}_{Dn}$ to Q_n or $\overline{Q}_n$	5.0	2.5	–	9.5	2.0	10.5	ns	3–6
t_{PHL}	Propagation Delay $\overline{C}_{Dn}$ or $\overline{S}_{Dn}$ to Q_n or $\overline{Q}_n$	5.0	2.5	–	10.0	2.0	11.5	ns	3–6

*Voltage Range 5.0 V is 5.0 V ±0.5 V.

AC OPERATING REQUIREMENTS

Symbol	Parameter	V_{CC}* (V)	74ACT T_A = +25°C, C_L = 50 pF		74ACT T_A = –40°C to +85°C, C_L = 50 pF	Unit	Fig. No.
			Typ	Guaranteed Minimum			
t_s	Set–up Time, HIGH or LOW J_n or $\overline{K}_n$ to CP_n	5.0	–	2.0	2.5	ns	3–9
t_h	Hold Time, HIGH or LOW J_n or $\overline{K}_n$ to CP_n	5.0	–	2.0	2.0	ns	3–9
t_w	Pulse Width CP_n or $\overline{C}_{Dn}$ or $\overline{S}_{Dn}$	5.0	–	5.0	6.0	ns	3–6

*Voltage Range 5.0 V is 5.0 V ±0.5 V.

AC OPERATING REQUIREMENTS (continued)

Symbol	Parameter	V_{CC}* (V)	74ACT T_A = +25°C C_L = 50 pF		74ACT T_A = −40°C to +85°C C_L = 50 pF	Unit	Fig. No.
			Typ	Guaranteed Minimum			
t_{rec}	Recovery TIme $\overline{C}_{Dn}$ or $\overline{S}_{Dn}$ to CP	5.0	–	0	0	ns	3–9

*Voltage Range 5.0 V is 5.0 V ±0.5 V.

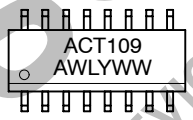
CAPACITANCE

Symbol	Parameter	Value Typ	Unit	Test Conditions
C_{IN}	Input Capacitance	4.5	pF	V_{CC} = 5.0 V
C_{PD}	Power Dissipation Capacitance	35	pF	V_{CC} = 5.0 V

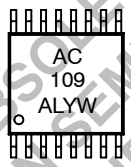
MARKING DIAGRAMS

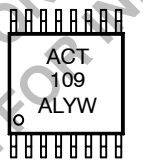
DIP−16

SO−16

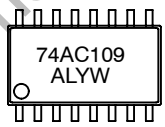


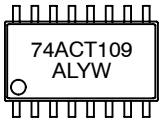
TSSOP−16





EIAJ−16

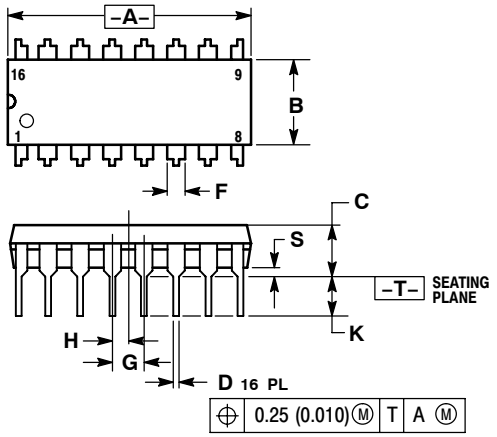




A = Assembly Location
WL, L = Wafer Lot
YY, Y = Year
WW, W = Work Week

PACKAGE DIMENSIONS

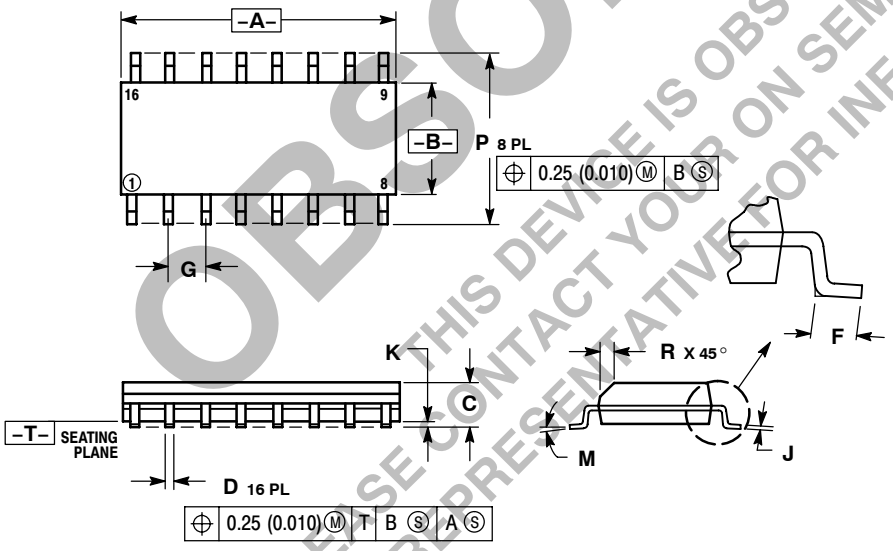
PDIP–16
N SUFFIX
16 PIN PLASTIC DIP PACKAGE
CASE 648–08
ISSUE R



NOTES:
1. DIMENSIONING AND TOLERANCING PER ANSI Y14.5M, 1982.
2. CONTROLLING DIMENSION: INCH.
3. DIMENSION L TO CENTER OF LEADS WHEN FORMED PARALLEL.
4. DIMENSION B DOES NOT INCLUDE MOLD FLASH.
5. ROUNDED CORNERS OPTIONAL.

	INCHES		MILLIMETERS	
DIM	MIN	MAX	MIN	MAX
A	0.740	0.770	18.80	19.55
B	0.250	0.270	6.35	6.85
C	0.145	0.175	3.69	4.44
D	0.015	0.021	0.39	0.53
F	0.040	0.70	1.02	1.77
G	0.100 BSC		2.54 BSC	
H	0.050 BSC		1.27 BSC	
J	0.008	0.015	0.21	0.38
K	0.110	0.130	2.80	3.30
L	0.295	0.305	7.50	7.74
M	0°	10°	0°	10°
S	0.020	0.040	0.51	1.01

SO–16
D SUFFIX
16 PIN PLASTIC SOIC PACKAGE
CASE 751B–05
ISSUE J

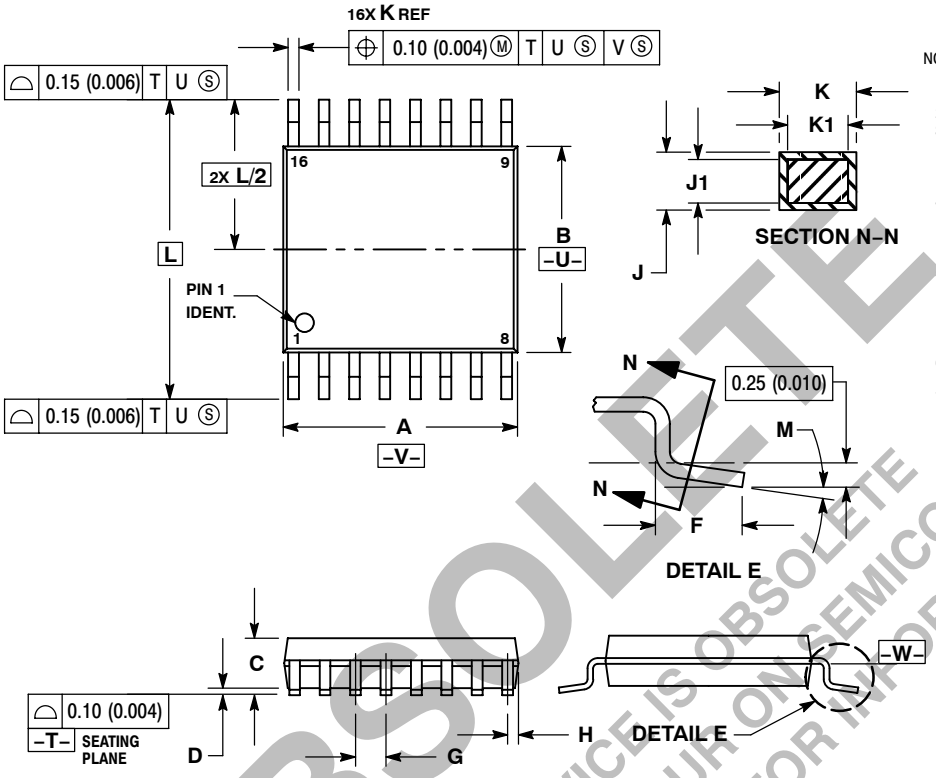


NOTES:
1. DIMENSIONING AND TOLERANCING PER ANSI Y14.5M, 1982.
2. CONTROLLING DIMENSION: MILLIMETER.
3. DIMENSIONS A AND B DO NOT INCLUDE MOLD PROTRUSION.
4. MAXIMUM MOLD PROTRUSION 0.15 (0.006) PER SIDE.
5. DIMENSION D DOES NOT INCLUDE DAMBAR PROTRUSION. ALLOWABLE DAMBAR PROTRUSION SHALL BE 0.127 (0.005) TOTAL IN EXCESS OF THE D DIMENSION AT MAXIMUM MATERIAL CONDITION.

	MILLIMETERS		INCHES	
DIM	MIN	MAX	MIN	MAX
A	9.80	10.00	0.386	0.393
B	3.80	4.00	0.150	0.157
C	1.35	1.75	0.054	0.068
D	0.35	0.49	0.014	0.019
F	0.40	1.25	0.016	0.049
G	1.27 BSC		0.050 BSC	
J	0.19	0.25	0.008	0.009
K	0.10	0.25	0.004	0.009
M	0°	7°	0°	7°
P	5.80	6.20	0.229	0.244
R	0.25	0.50	0.010	0.019

PACKAGE DIMENSIONS

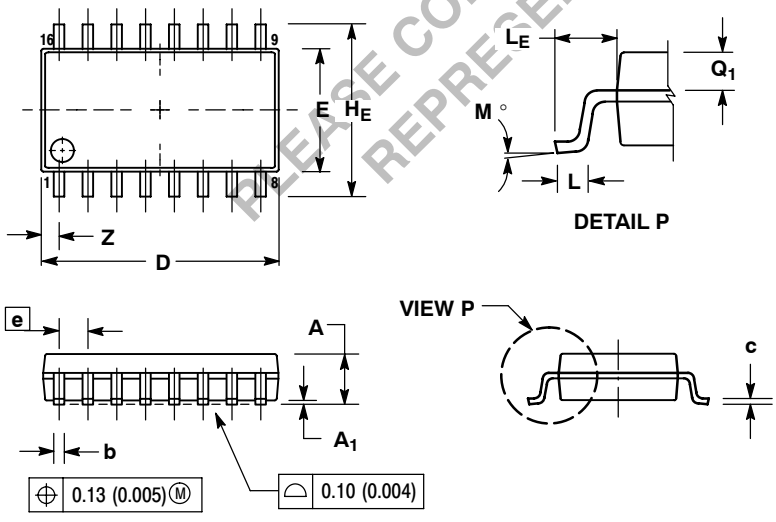
TSSOP–16
DT SUFFIX
16 PIN PLASTIC TSSOP PACKAGE
CASE948F–01
ISSUE O



NOTES:
1. DIMENSIONING AND TOLERANCING PER ANSI Y14.5M, 1982.
2. CONTROLLING DIMENSION: MILLIMETER.
3. DIMENSION A DOES NOT INCLUDE MOLD FLASH. PROTRUSIONS OR GATE BURRS. MOLD FLASH OR GATE BURRS SHALL NOT EXCEED 0.15 (0.006) PER SIDE.
4. DIMENSION B DOES NOT INCLUDE INTERLEAD FLASH OR PROTRUSION. INTERLEAD FLASH OR PROTRUSION SHALL NOT EXCEED 0.25 (0.010) PER SIDE.
5. DIMENSION K DOES NOT INCLUDE DAMBAR PROTRUSION. ALLOWABLE DAMBAR PROTRUSION SHALL BE 0.08 (0.003) TOTAL IN EXCESS OF THE K DIMENSION AT MAXIMUM MATERIAL CONDITION.
6. TERMINAL NUMBERS ARE SHOWN FOR REFERENCE ONLY.
7. DIMENSION A AND B ARE TO BE DETERMINED AT DATUM PLANE –W–.

	MILLIMETERS		INCHES	
DIM	MIN	MAX	MIN	MAX
A	4.90	5.10	0.193	0.200
B	4.30	4.50	0.169	0.177
C	---	1.20	---	0.047
D	0.05	0.15	0.002	0.006
F	0.50	0.75	0.020	0.030
G	0.65 BSC		0.026 BSC	
H	0.18	0.28	0.007	0.011
J	0.09	0.20	0.004	0.008
J1	0.09	0.16	0.004	0.006
K	0.19	0.30	0.007	0.012
K1	0.19	0.25	0.007	0.010
L	6.40 BSC		0.252 BSC	
M	0 °	8 °	0 °	8 °

EIAJ–16
M SUFFIX
16 PIN PLASTIC EIAJ PACKAGE
CASE966–01
ISSUE O



NOTES:
1. DIMENSIONING AND TOLERANCING PER ANSI Y14.5M, 1982.
2. CONTROLLING DIMENSION: MILLIMETER.
3. DIMENSIONS D AND E DO NOT INCLUDE MOLD FLASH OR PROTRUSIONS AND ARE MEASURED AT THE PARTING LINE. MOLD FLASH OR PROTRUSIONS SHALL NOT EXCEED 0.15 (0.006) PER SIDE.
4. TERMINAL NUMBERS ARE SHOWN FOR REFERENCE ONLY.
5. THE LEAD WIDTH DIMENSION (b) DOES NOT INCLUDE DAMBAR PROTRUSION. ALLOWABLE DAMBAR PROTRUSION SHALL BE 0.08 (0.003) TOTAL IN EXCESS OF THE LEAD WIDTH DIMENSION AT MAXIMUM MATERIAL CONDITION. DAMBAR CANNOT BE LOCATED ON THE LOWER RADIUS OR THE FOOT. MINIMUM SPACE BETWEEN PROTRUSIONS AND ADJACENT LEAD TO BE 0.46 (0.018).

	MILLIMETERS		INCHES	
DIM	MIN	MAX	MIN	MAX
A	---	2.05	---	0.081
A_1	0.05	0.20	0.002	0.008
b	0.35	0.50	0.014	0.020
c	0.18	0.27	0.007	0.011
D	9.90	10.50	0.390	0.413
E	5.10	5.45	0.201	0.215
e	1.27 BSC		0.050 BSC	
H_E	7.40	8.20	0.291	0.323
L	0.50	0.85	0.020	0.033
L_E	1.10	1.50	0.043	0.059
M	0 °	10 °	0 °	10 °
Q_1	0.70	0.90	0.028	0.035
Z	---	0.78	---	0.031

PUBLICATION ORDERING INFORMATION

LITERATURE FULFILLMENT:
Literature Distribution Center for ON Semiconductor
P.O. Box 5163, Denver, Colorado 80217 USA
Phone: 303−675−2175 or 800−344−3860 Toll Free USA/Canada
Fax: 303−675−2176 or 800−344−3867 Toll Free USA/Canada
Email: orderlit@onsemi.com

N. American Technical Support: 800−282−9855 Toll Free USA/Canada
Europe, Middle East and Africa Technical Support:
Phone: 421 33 790 2910
Japan Customer Focus Center
Phone: 81−3−5773−3850

ON Semiconductor Website: **www.onsemi.com**

Order Literature: http://www.onsemi.com/orderlit

For additional information, please contact your local Sales Representative

MC74AC109/D